



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

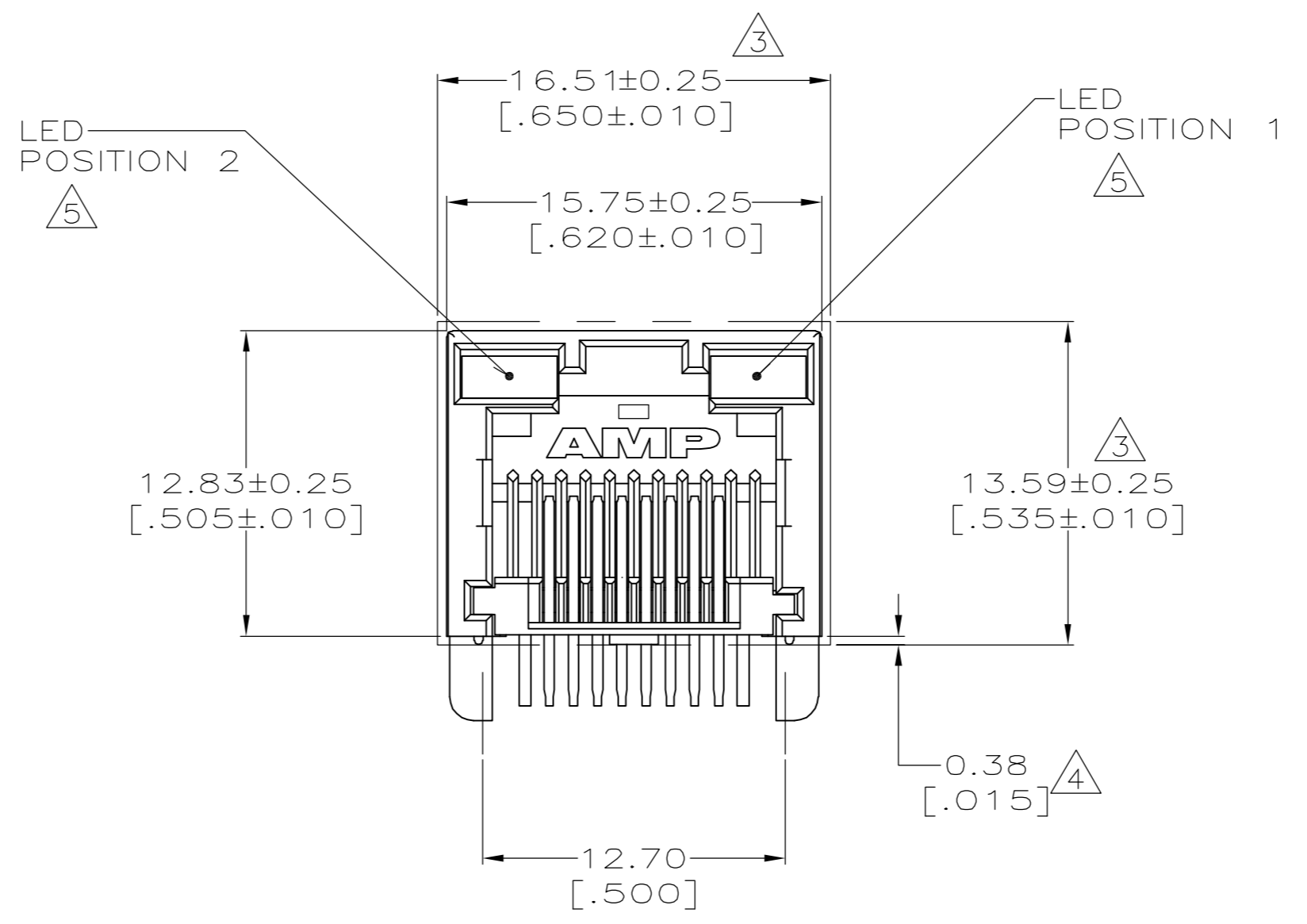
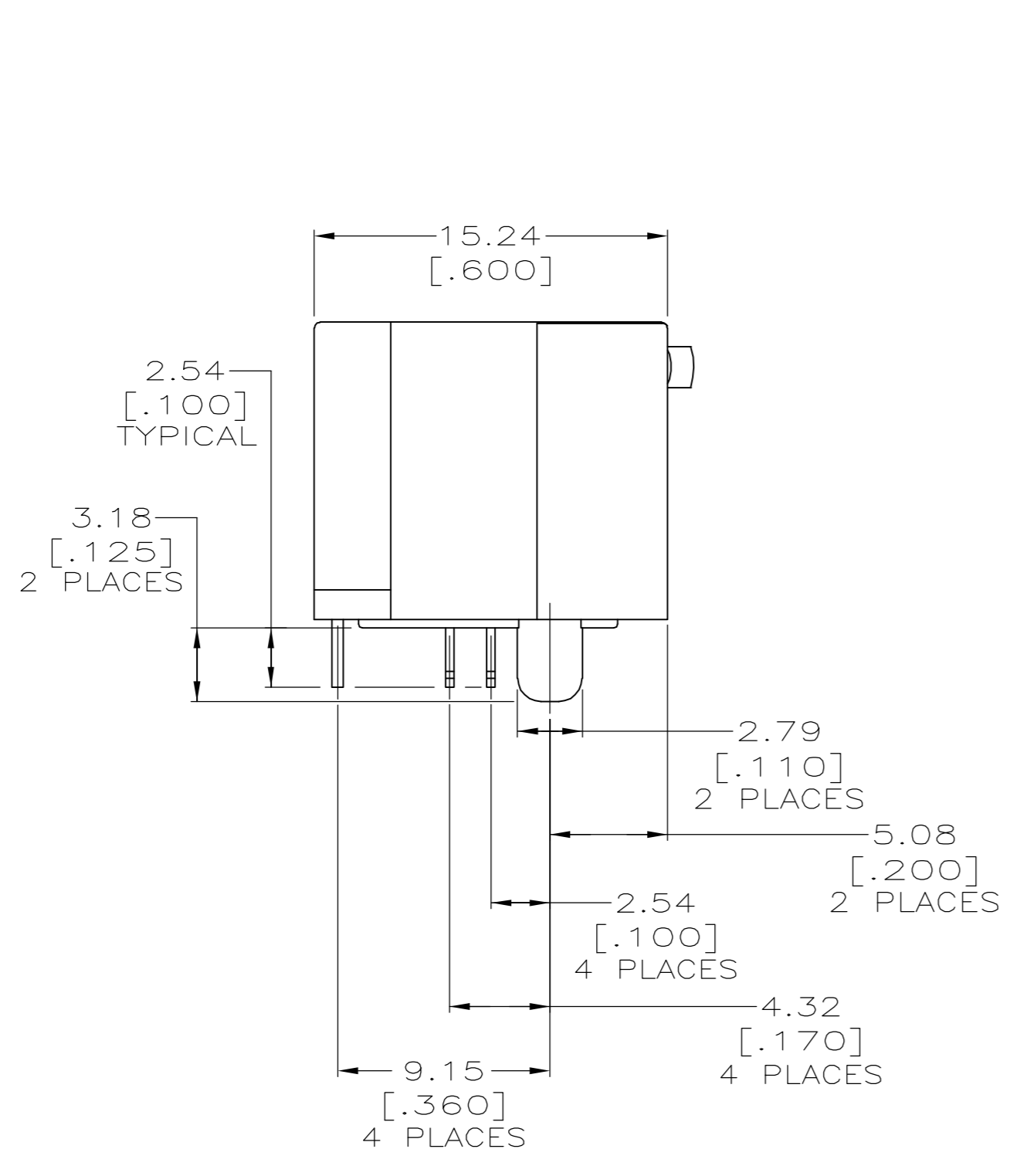
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

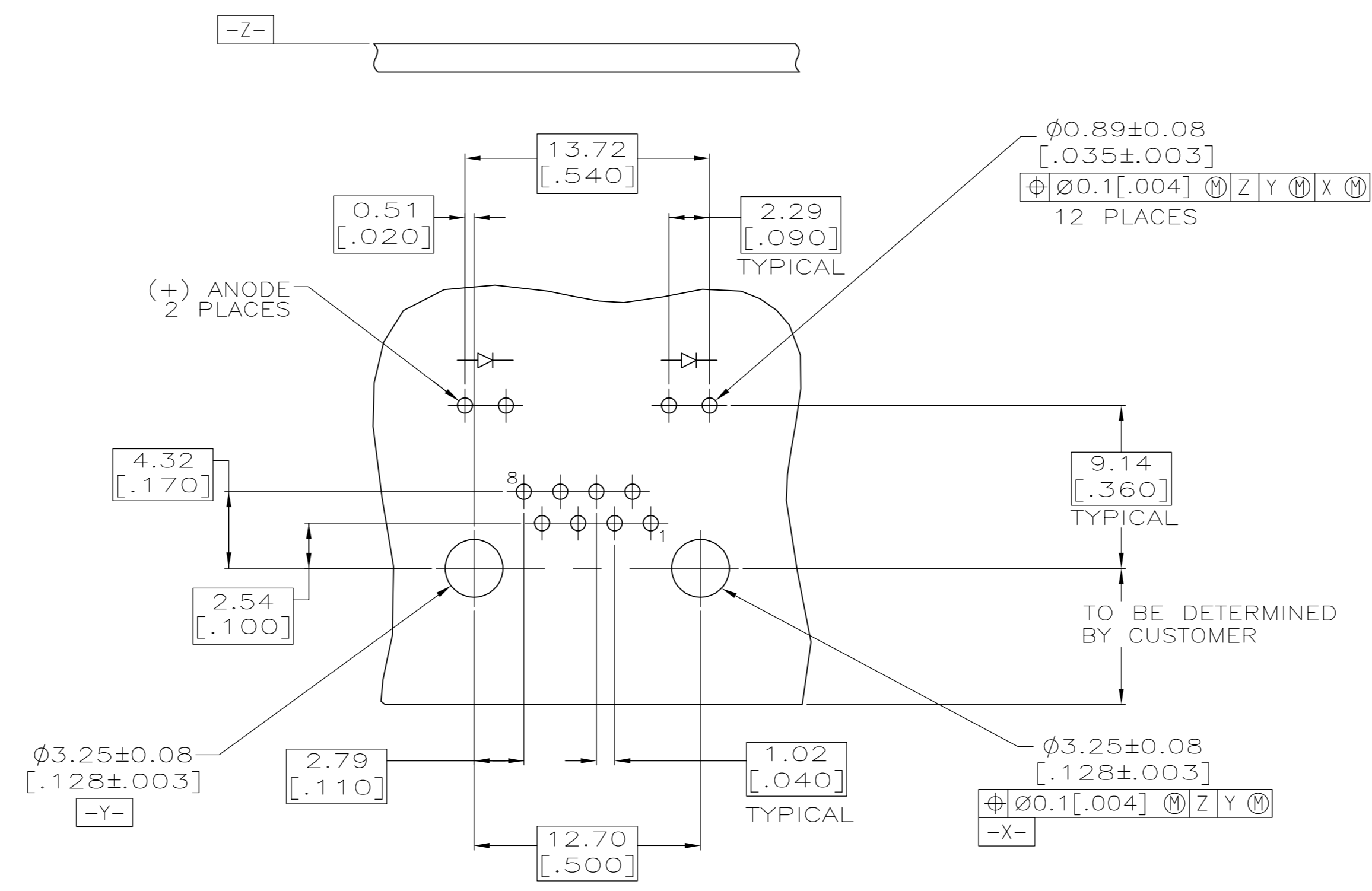
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



LOC		DIST		REVISIONS			
P	LR	DESCRIPTION	DATE	OWN	APVD		
A	REV PER EC	OS11-0201-04	15JUN2005	LV	SF		



- △ MATERIAL:  
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.  
 TERMINALS - .36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL.  
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, .51 x .51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89µm[.0003500] THICK Sn/Cu OVER 2.03µm[.000080] THICK Ag OVER 1.02 µm[.000040] THICK Cu OVER 3.56µm[.000140] THICK Ni OVER 1.02µm[.000040] Cu UNDERPLATE.
2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN BOTTOM OF CONNECTOR AND BOTTOM PANEL OPENING.
- △ SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
6. THIS MODULAR JACK WITH INTEGRATED LED IS IR REFLOW SOLDERING PROCESS COMPATIBLE. (230°C MAX., FOR 10 SEC MAX. DURATION).



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)

GREEN POSITION 2	GREEN POSITION 1	6364139-5
INDICATOR COLOR		PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	OWN: L. VARELA - DOCKS 15JUN2005	CHK: J. WESTMAN 15JUN2005	APVD: S. FLICKINGER 15JUN2005	NAME: S. FLICKINGER	TYCO ELECTRONICS CORPORATION	Tyco Electronics Corporation Harrisburg, Pa 17105-3608
0. PLC ± -	1. PLC ± -	2. PLC ± 0.25[.01]	3. PLC ± 0.13[.005]	4. PLC ± -	ANGLES ± -	PRODUCT SPEC: 108-1163-4	APPLICATION SPEC: 114-2154
MATERIAL: △	FINISH: △	WEIGHT: -	SIZE: A1	CAGE CODE: 00779	DRAWING NO: 6364139	RESTRICTED TO: -	CUSTOMER DRAWING
SCALE: 4:1		SHEET: 1 OF 1		REV: A			